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/ Mari	(RP)500 04/	2003)			Application Number	10/743,527			
INFORMATION DISCLOSURE					Filing Date	December 22, 2003			
					First Named Inventor	Xu			
	STATEMENT BY APPLICANT (Use as many sheets as necessary)				Group Art Unit	2841			
					Examiner Name	(notyet assigned) HOA C. NGUYEN			
	Sheet	1	of	1	Attorney Docket Number	042933/270304			

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\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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